

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L3	25390	pakag\$3 amd mold\$3 and (die or chip) and frame and window.clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/16 10:16
L4	1266	I3 and semiconductor and light	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/16 10:17
L5	372	I3 and semiconductor and light.clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/16 10:17